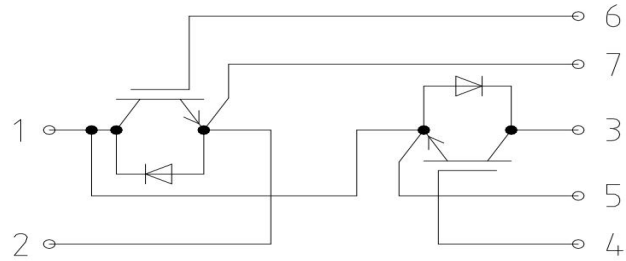


PRODUCT FEATURES

- IGBT CHIP(Trench+FS)
- Low saturation voltage and positive temperature coefficient
- Fast switching and short tail current
- Free wheeling diodes with fast and soft reverse recovery
- Ultra Low Loss,High Ruggedness
- High short circuit capability


APPLICATIONS

- High frequency switching application
- Medical applications
- Motion/servo control
- UPS systems


IGBT

 ABSOLUTE MAXIMUM RATINGS($T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/ Test Conditions	Values	Unit
V_{CES}	Collector Emitter Voltage	1700	V
V_{GES}	Gate Emitter Voltage	± 20	
I_c	DC Collector Current	$T_C = 25^\circ\text{C}, T_{Jmax} = 175^\circ\text{C}$	246
		$T_C = 100^\circ\text{C}, T_{Jmax} = 175^\circ\text{C}$	150
I_{CM}	Repetitive Peak Collector Current	$t_p = 1\text{ms}$	300
P_{tot}	Power Dissipation Per IGBT	$T_C = 25^\circ\text{C}, T_{Jmax} = 175^\circ\text{C}$	1.2

Diode

 ABSOLUTE MAXIMUM RATINGS($T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/ Test Conditions	Values	Unit
V_{RRM}	Repetitive Reverse Voltage	1700	V
$I_{F(AV)}$	Average Forward Current	150	A
I_{FRM}	Repetitive Peak Forward Current	$t_p = 1\text{ms}$	
I^2t		$T_J = 150^\circ\text{C}, t = 10\text{ms}, V_R = 0\text{V}$	16.2

 MODULE CHARACTERISTICS($T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/ Test Conditions	Values	Unit	
T_{Jmax}	Max. Junction Temperature	175	$^\circ\text{C}$	
T_{Jop}	Operating Temperature	-40~150		
T_{stg}	Storage Temperature	-40~125		
V_{isol}	Isolation Breakdown Voltage	AC, 50Hz(R.M.S), $t = 1\text{minute}$	4000	V
CTI	Comparative Tracking Index		>200	
Torque	to heatsink	Recommended (M6)	3~5	Nm
	to terminal	Recommended (M6)	3~5	Nm
Weight			320	g

IGBT

 ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/ Test Conditions		Min.	Typ.	Max.	Unit
$V_{GE(th)}$	Gate Emitter Threshold Voltage	$V_{CE}=V_{GE}, I_C=6\text{mA}$	5.5	6.0	6.5	V
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	$I_C=150\text{A}, V_{GE}=15\text{V}, T_J=25^\circ\text{C}$		1.85	2.2	
		$I_C=150\text{A}, V_{GE}=15\text{V}, T_J=125^\circ\text{C}$		2.05		
		$I_C=150\text{A}, V_{GE}=15\text{V}, T_J=150^\circ\text{C}$		2.15		
I_{CES}	Collector Leakage Current	$V_{CE}=1700\text{V}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$			1	mA
		$V_{CE}=1700\text{V}, V_{GE}=0\text{V}, T_J=150^\circ\text{C}$			10	mA
I_{GES}	Gate Leakage Current	$V_{CE}=0\text{V}, V_{GE}=\pm 20\text{V}, T_J=25^\circ\text{C}$			± 500	nA
R_{gint}	Integrated Gate Resistor			1.8		Ω
Q_g	Gate Charge	$V_{CE}=900\text{V}, I_C=150\text{A}, V_{GE}=15\text{V}$		1.2		μC
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$		14.2		nF
C_{res}	Reverse Transfer Capacitance			450		pF
$t_{d(on)}$	Turn on Delay Time	$V_{CC}=900\text{V}, I_C=150\text{A}$ $R_G=3.6\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	120		ns
			$T_J=150^\circ\text{C}$	140		ns
t_r	Rise Time	$V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	70		ns
			$T_J=150^\circ\text{C}$	80		ns
$t_{d(off)}$	Turn off Delay Time	$V_{CC}=900\text{V}, I_C=150\text{A}$ $R_G=3.6\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	502		ns
			$T_J=150^\circ\text{C}$	550		ns
t_f	Fall Time	$V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	230		ns
			$T_J=150^\circ\text{C}$	340		ns
E_{on}	Turn on Energy	$V_{CC}=900\text{V}, I_C=150\text{A}$ $R_G=3.6\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	50		mJ
			$T_J=150^\circ\text{C}$	68		mJ
E_{off}	Turn off Energy	$V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	25		mJ
			$T_J=150^\circ\text{C}$	40		mJ
I_{sc}	Short Circuit Current	$t_{psc}\leq 10\mu\text{S}, V_{GE}=15\text{V}$ $T_J=150^\circ\text{C}, V_{CC}=900\text{V}$		800		A
R_{thJC}	Junction to Case Thermal Resistance (Per IGBT)				0.14	K /W

Diode-inverter

ELECTRICAL CHARACTERISTICS (T_C =25°C unless otherwise specified)

Symbol	Parameter/ Test Conditions	Min.	Typ.	Max.	Unit	
V _F	Collector Emitter Voltage	I _F =450A, V _{GE} =0V, T _J = 2 5 °C		1.8	2.2	V
		I _F =450A, V _{GE} =0V, T _J = 1 2 5 °C		1.95		
		I _F =450A, V _{GE} =0V, T _J = 1 5 0 °C		1.9		
T _{rr}	Gate Emitter Voltage		800		nS	
I _{RRM}	DC Collector Current dI _F /dt=-2100A/μs T _J =150°C		160		A	
Q _{RR}			85		μC	
E _{rec}			40		mJ	
R _{thJCD}		Junction to Case Thermal Resistance (Per Diode)			0.24	kW

IGBT Typical Performance

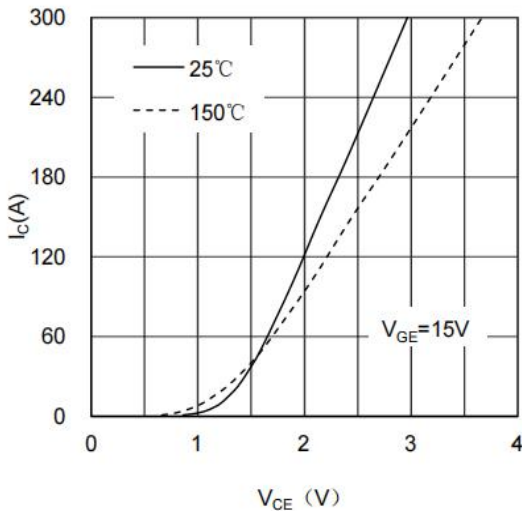


Figure1 Typical Output Characteristics IGBT-inverter

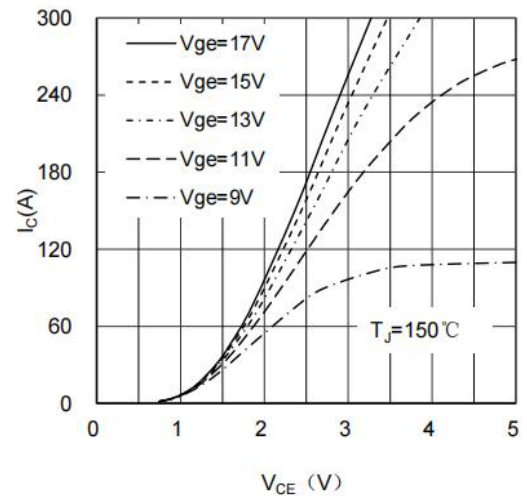


Figure2 Typical Output Characteristics IGBT-inverter

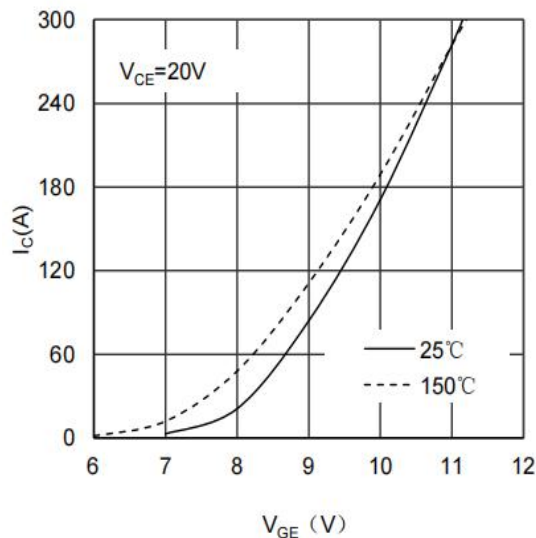


Figure3 Typical Transfer characteristics IGBT-inverter

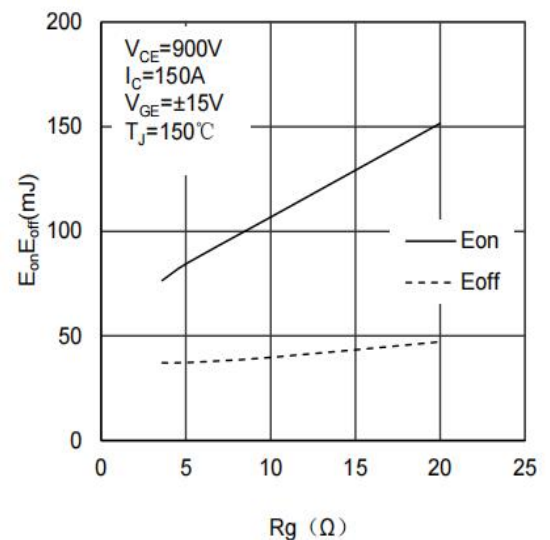


Figure4 Switching Energy vs Gate Resistor IGBT-inverter

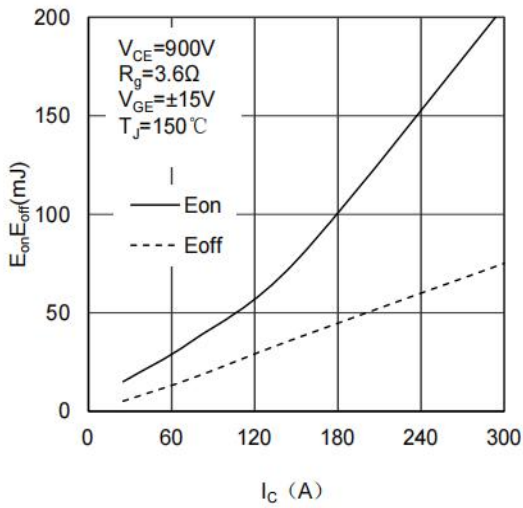


Figure5 Switching Energy vs Collector Current IGBT-inverter

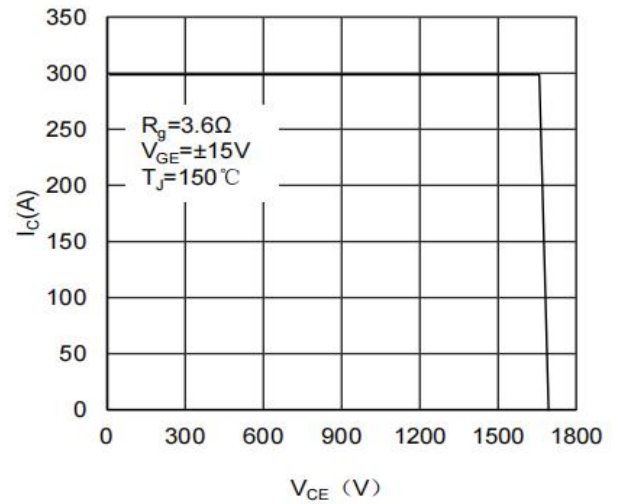


Figure6 Reverse Biased Safe Operating Area IGBT-inverter

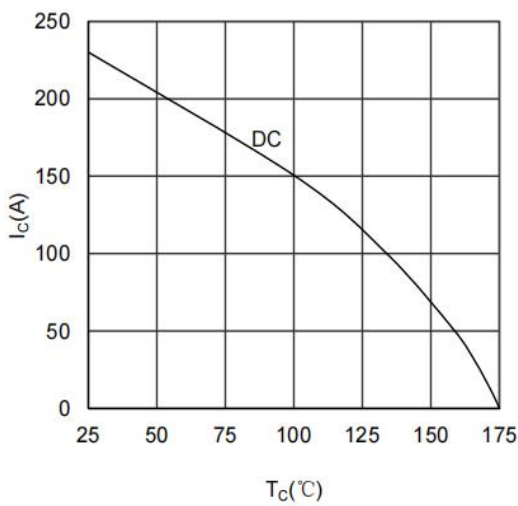


Figure7 Collector Current vs Case temperature IGBT-inverter

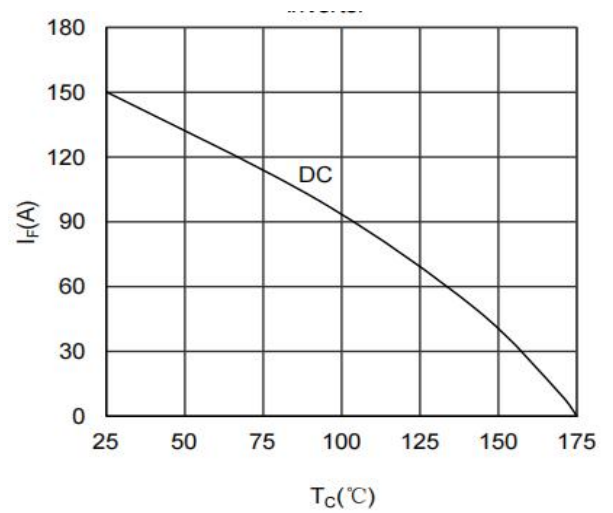


Figure8 Forward current vs Case temperature Diode-inverter

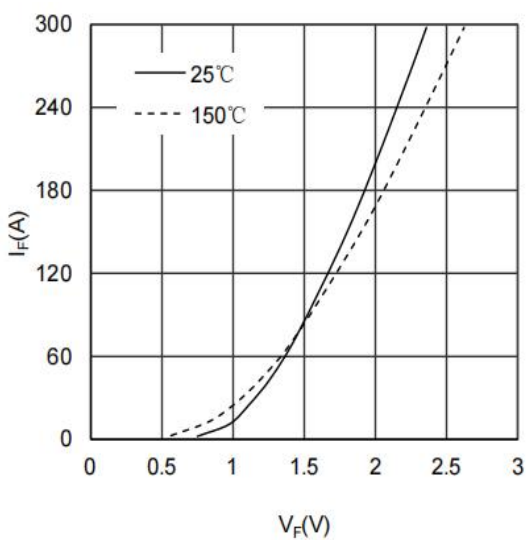


Figure9 Diode Forward Characteristics Diode-inverter

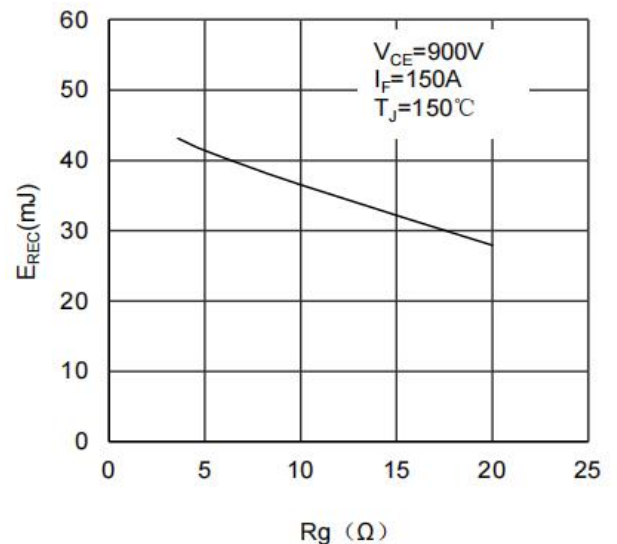


Figure10 Switching Energy vs Gate Resistor Diode-inverter

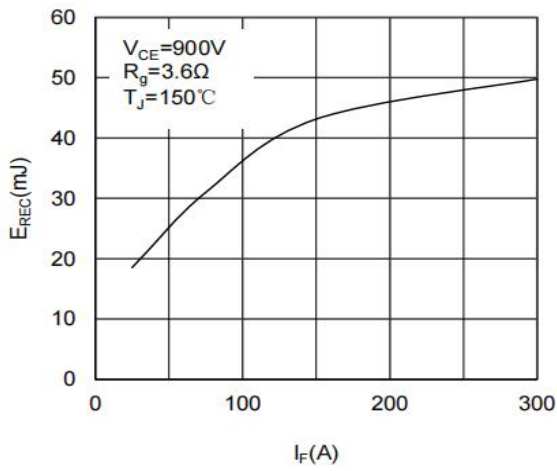


Figure11 Switching Energy vs Forward Current Diode-inverter

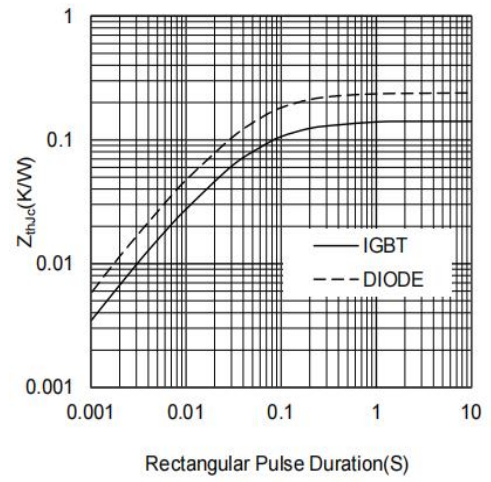
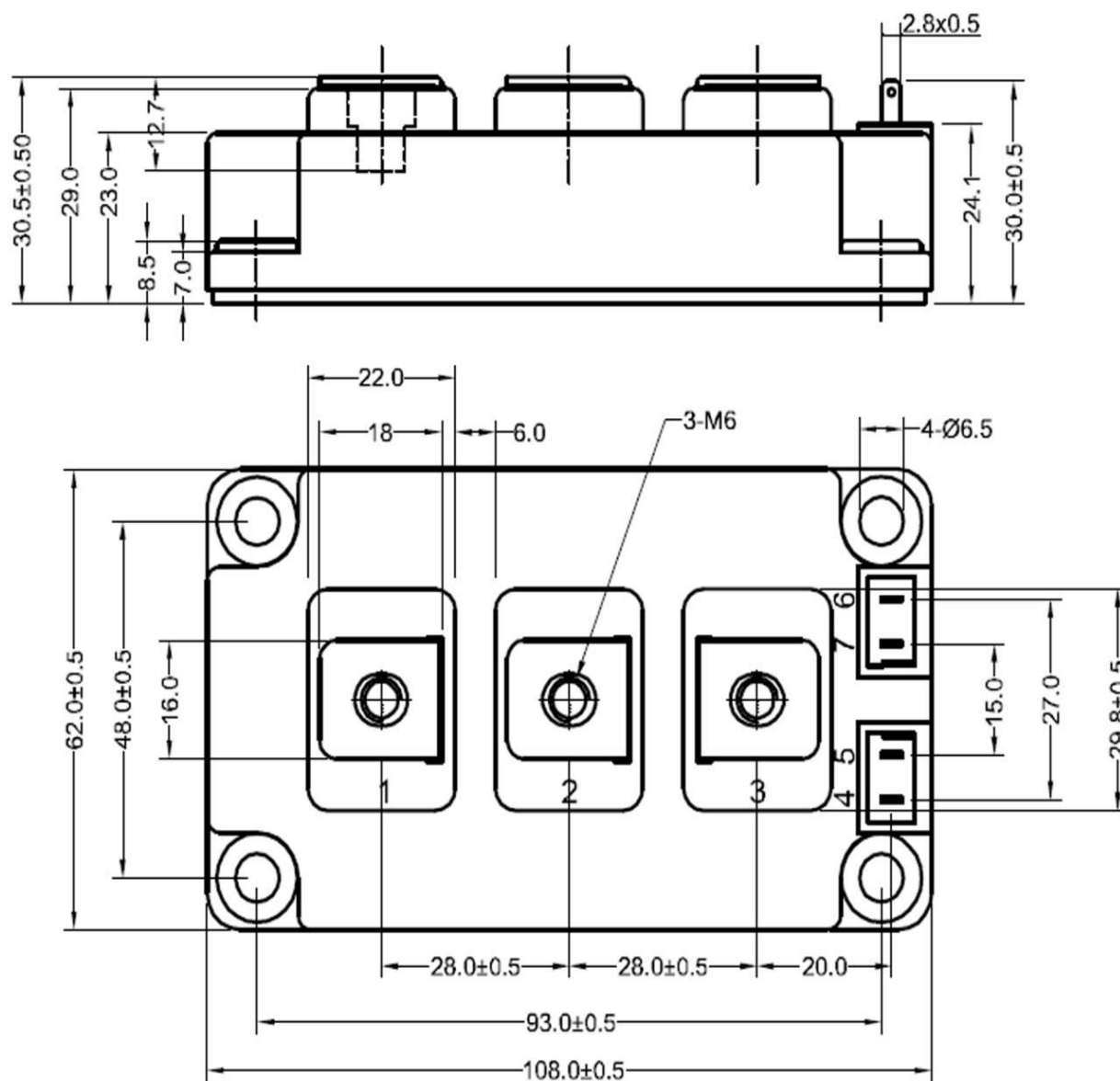


Figure12 Transient Thermal Impedance of Diode and IGBT-inverter

Package Dimensions: 62MM



Dimensions in (mm)
Figure 13 Package Outline

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